

## N-Channel Power MOSFET (7A, 600Volts)

### DESCRIPTION

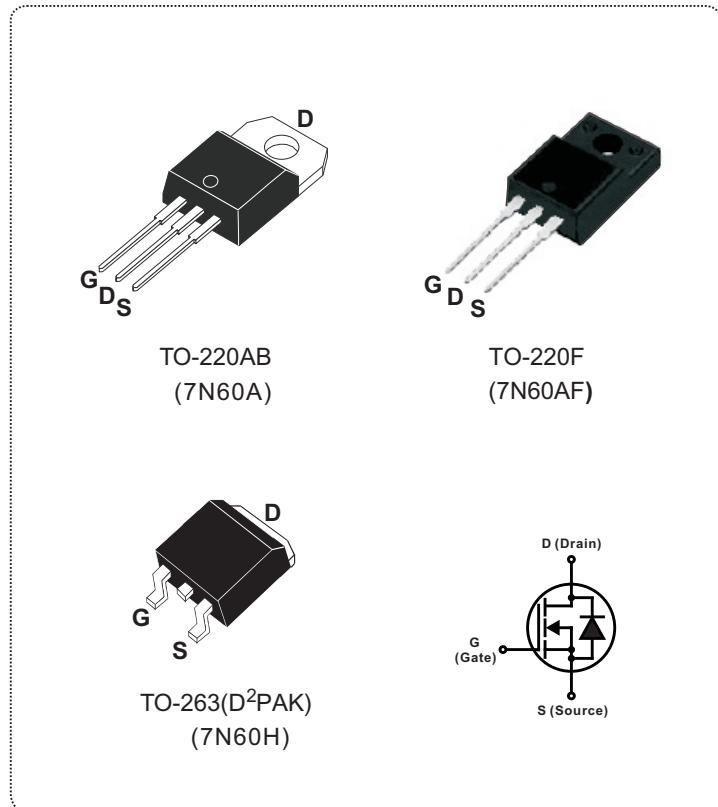
The Nell 7N60 is a three-terminal silicon device with current conduction capability of 7A, fast switching speed, low on-state resistance, breakdown voltage rating of 600V ,and max. threshold voltage of 4 volts.

They are designed for use in applications. such as switched mode power supplies, DC to DC converters, PWM motor controls, bridge circuits, and general purpose switching applications .

### FEATURES

- $R_{DS(ON)} = 1.2\Omega @ V_{GS} = 10V$
- Ultra low gate charge(38nC max.)
- Low reverse transfer capacitance ( $C_{RSS} = 16pF$  typical)
- Fast switching capability
- 100% avalanche energy specified
- Improved dv/dt capability
- 150°C operation temperature

PRODUCT SUMMARY	
$I_D$ (A)	7
$V_{DSS}$ (V)	600
$R_{DS(ON)}$ ( $\Omega$ )	1.2 @ $V_{GS} = 10V$
$Q_G$ (nC) max.	38



### ABSOLUTE MAXIMUM RATINGS ( $T_C = 25^\circ C$ unless otherwise specified)

SYMBOL	PARAMETER	TEST CONDITIONS		VALUE	UNIT	
$V_{DSS}$	Drain to Source voltage	$T_J=25^\circ C$ to $150^\circ C$	$R_{GS}=20K\Omega$	600	V	
$V_{DGR}$	Drain to Gate voltage			600		
$V_{GS}$	Gate to Source voltage			$\pm 30$		
$I_D$	Continuous Drain Current	$T_C=25^\circ C$	$T_C=100^\circ C$	7	A	
				4.3		
$I_{DM}$	Pulsed Drain current(Note 1)			28		
$I_{AR}$	Avalanche current(Note 1)			7		
$E_{AR}$	Repetitive avalanche energy(Note 1)	$I_{AR}=7A, R_{GS}=50\Omega, V_{GS}=10V$		14	mJ	
$E_{AS}$	Single pulse avalanche energy(Note 2)	$I_{AS}=7A, L=19.5mH$		500		
$dv/dt$	Peak diode recovery $dv/dt$ (Note 3)			4.5	V /ns	
$P_D$	Total power dissipation	$T_C=25^\circ C$	TO-220AB/TO-263	140	W	
			TO-220F	48		
$T_J$	Operation junction temperature			-55 to 150	°C	
$T_{STG}$	Storage temperature			-55 to 150		
$T_L$	Maximum soldering temperature, for 10 seconds	1.6mm from case		300		
Mounting torque, #6-32 or M3 screw				10 (1.1)	lbf-in (N·m)	

Note: 1.Repetitive rating: pulse width limited by junction temperature..

2. $I_{AS} = 7A, V_{DD} = 50V, L = 19.5mH, R_{GS} = 25\Omega$ , starting  $T_J=25^\circ C$ .

3. $I_{SD} \leq 7A$ ,  $di/dt \leq 200A/\mu s$ ,  $V_{DD} \leq V_{(BR)DSS}$ , starting  $T_J=25^\circ C$ .

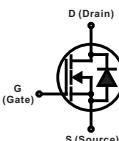
THERMAL RESISTANCE						
SYMBOL	PARAMETER		Min.	Typ.	Max.	UNIT
$R_{th(j-c)}$	Thermal resistance, junction to case	TO-220AB/TO-263			0.85	$^{\circ}\text{C}/\text{W}$
		TO-220F			2.5	
$R_{th(j-a)}$	Thermal resistance, junction to ambient	TO-220AB/TO-263			62.5	$^{\circ}\text{C}/\text{W}$
		TO-220F			62.5	

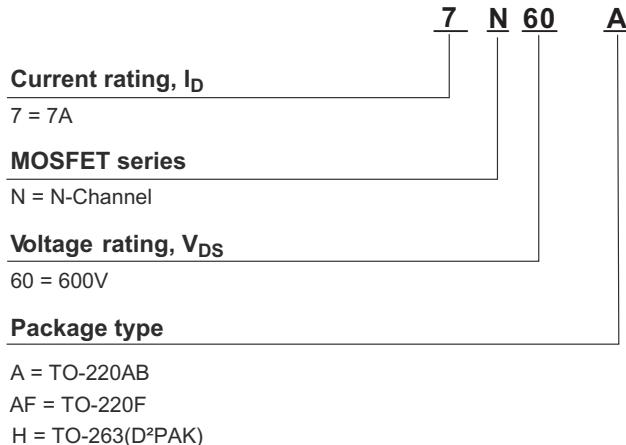
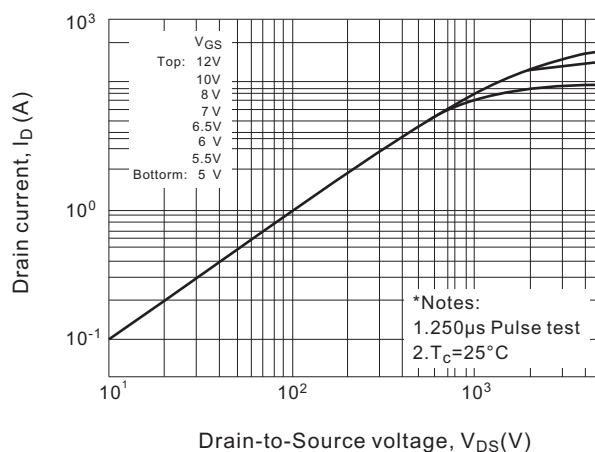
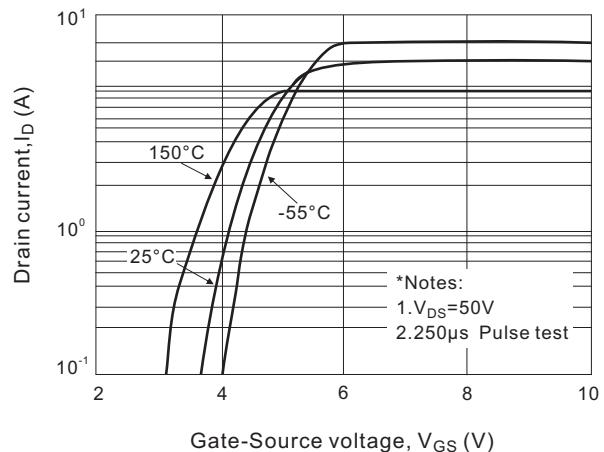
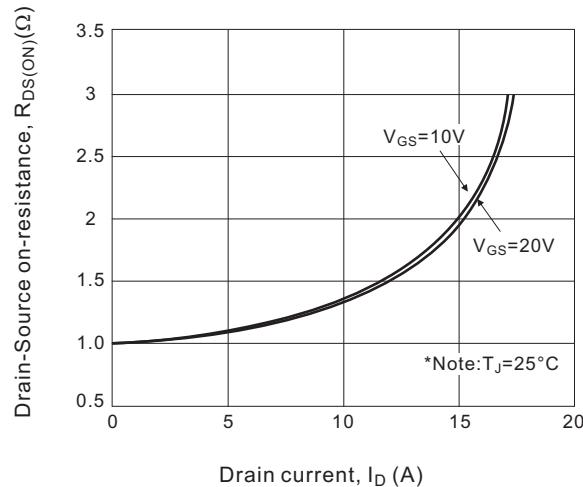
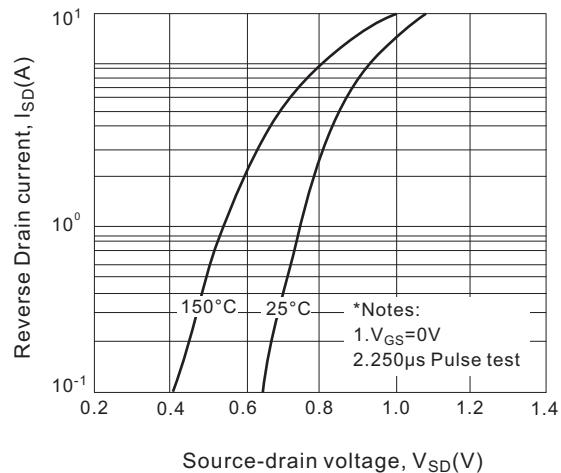
ELECTRICAL CHARACTERISTICS ( $T_C = 25^{\circ}\text{C}$ unless otherwise specified)						
SYMBOL	PARAMETER	TEST CONDITIONS	Min.	Typ.	Max.	UNIT
$V_{(BR)DSS}$	Drain to source breakdown voltage	$I_D = 250\mu\text{A}, V_{GS} = 0\text{V}$	600			V
$\Delta V_{(BR)DSS}/\Delta T_J$	Breakdown voltage temperature coefficient	$I_D = 250\mu\text{A}, V_{DS}=V_{GS}$		0.53		$\text{V}/^{\circ}\text{C}$
$I_{DSS}$	Drain to source leakage current	$V_{DS}=600\text{V}, V_{GS}=0\text{V}$	$T_C = 25^{\circ}\text{C}$		10	$\mu\text{A}$
		$V_{DS}=480\text{V}, V_{GS}=0\text{V}$	$T_C=125^{\circ}\text{C}$		100	
$I_{GSS}$	Gate to source forward leakage current	$V_{GS} = 30\text{V}, V_{DS} = 0\text{V}$			100	$\text{nA}$
	Gate to source reverse leakage current	$V_{GS} = -30\text{V}, V_{DS} = 0\text{V}$			-100	
$R_{DS(\text{ON})}$	Static drain to source on-state resistance	$I_D = 3.5\text{A}, V_{GS} = 10\text{V}$		0.95	1.2	$\Omega$
$V_{GS(\text{TH})}$	Gate threshold voltage	$V_{GS}=V_{DS}, I_D=250\mu\text{A}$	2		4	V
$C_{ISS}$	Input capacitance	$V_{DS} = 25\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$			1400	$\text{pF}$
$C_{OSS}$	Output capacitance				180	
$C_{RSS}$	Reverse transfer capacitance			16	21	
$t_{d(\text{ON})}$	Turn-on delay time	$V_{DD} = 300\text{V}, V_{GS} = 10\text{V}, I_D = 7\text{A}, R_{GS} = 25\Omega$ (Note 1, 2)			70	$\text{ns}$
$t_r$	Rise time				170	
$t_{d(\text{OFF})}$	Turn-off delay time				140	
$t_f$	Fall time				130	
$Q_G$	Total gate charge			28	38	$\text{nC}$
$Q_{GS}$	Gate to source charge	$V_{DD} = 480\text{V}, V_{GS} = 10\text{V}, I_D = 7\text{A}$ (Note 1, 2)		7		
$Q_{GD}$	Gate to drain charge (Miller charge)			14		

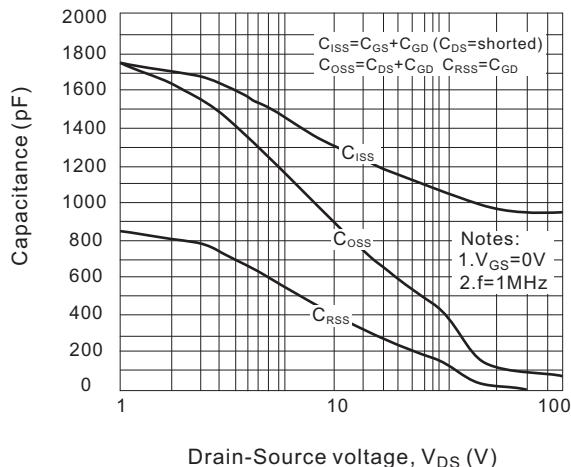
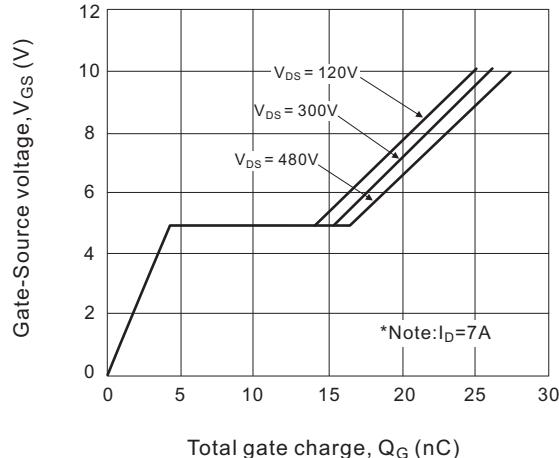
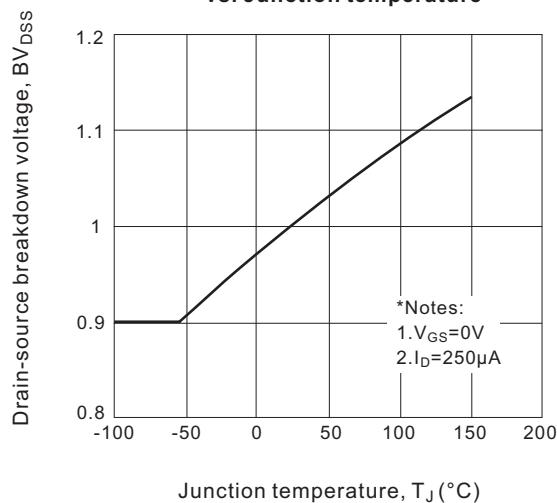
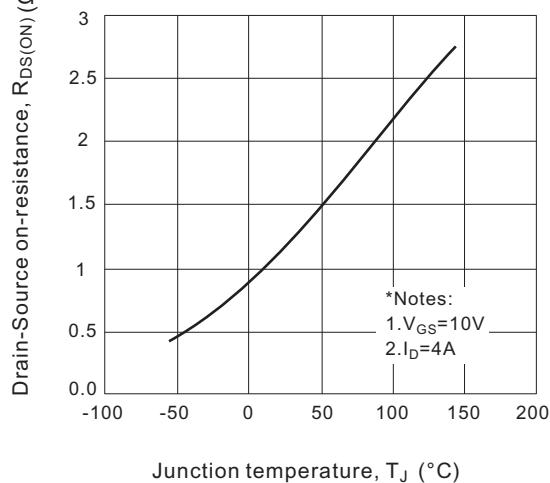
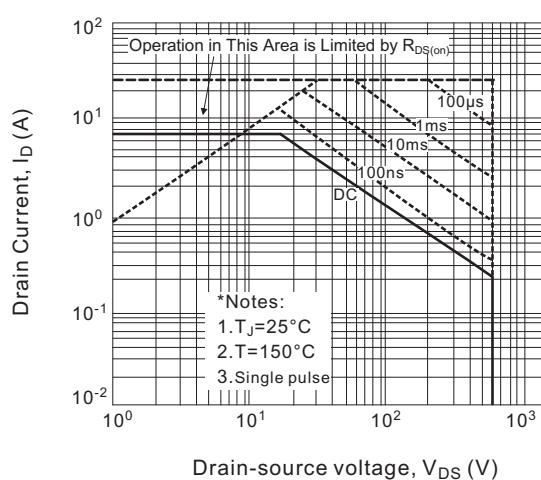
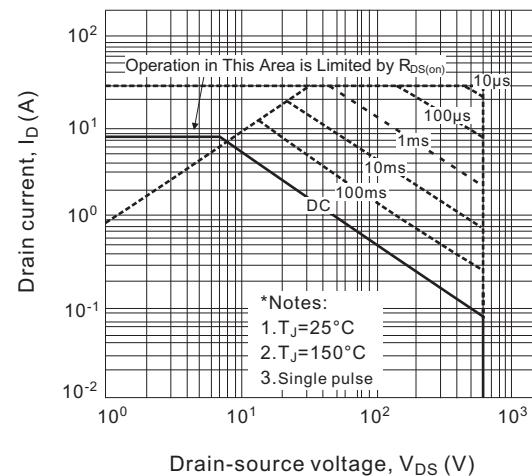
SOURCE TO DRAIN DIODE RATINGS AND CHARACTERISTICS ( $T_C = 25^{\circ}\text{C}$ unless otherwise specified)						
SYMBOL	PARAMETER	TEST CONDITIONS	Min.	Typ.	Max.	UNIT
$V_{SD}$	Diode forward voltage	$I_{SD} = 7\text{A}, V_{GS} = 0\text{V}$			1.4	V
$I_s (I_{SD})$	Continuous source to drain current	Integral reverse P-N junction diode in the MOSFET			7	A
$I_{SM}$	Pulsed source current				28	
$t_{rr}$	Reverse recovery time	$I_{SD} = 7\text{A}, V_{GS} = 0\text{V}, dI_F/dt = 100\text{A}/\mu\text{s}$		320		ns
$Q_{rr}$	Reverse recovery charge			2.4		$\mu\text{C}$

Note: 1. Pulse test: Pulse width  $\leq 300\mu\text{s}$ , duty cycle  $\leq 2\%$ .

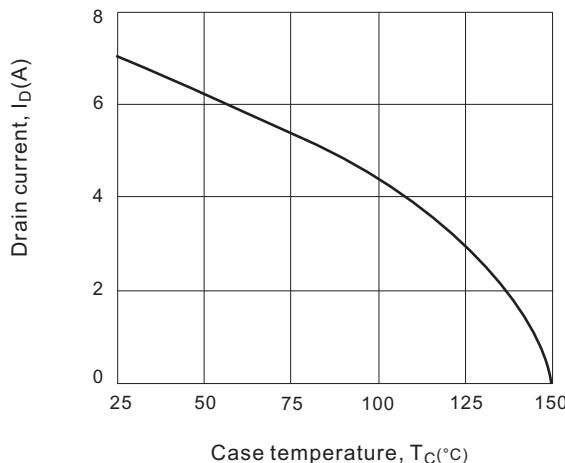
2. Essentially independent of operating temperature.



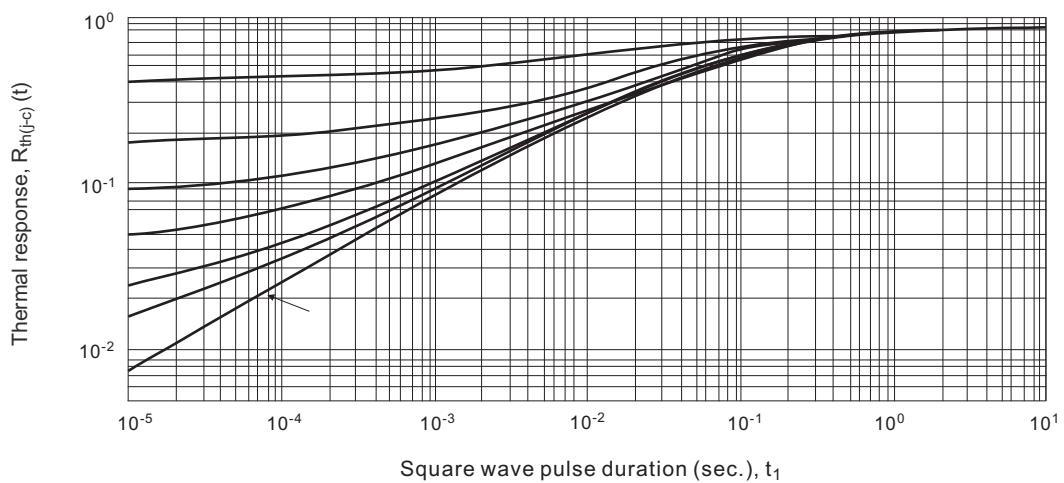
**ORDERING INFORMATION SCHEME**

**Fig.1 On-State characteristics**

**Fig.2 Transfer characteristics**

**Fig.3 On-resistance variation vs. drain current and gate voltage**

**Fig.4 Body diode forward voltage variation with source current and temperature**


**Fig.5 Capacitance characteristics**

**Fig.6 Gate charge characteristics**

**Fig.7 Breakdown voltage variation vs. Junction temperature**

**Fig.8 On-resistance variation vs. Junction temperature**

**Fig.9 Maximum safe operating area for TO-220**

**Fig.10 Maximum safe operating area for TO-220F**


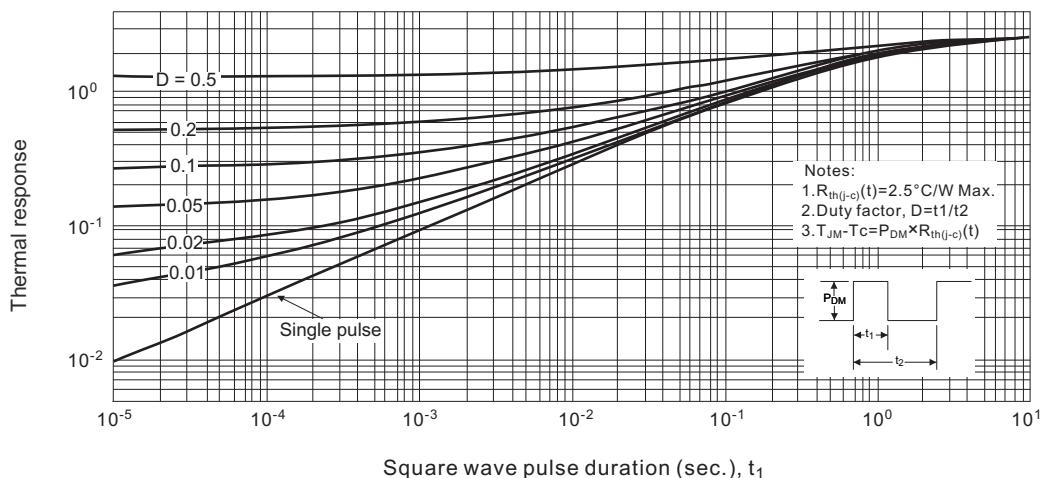
**Fig.11 Maximum drain current vs. case temperature**



**Fig.12 Transient thermal response curve (for 7N60A & 7N60H)**

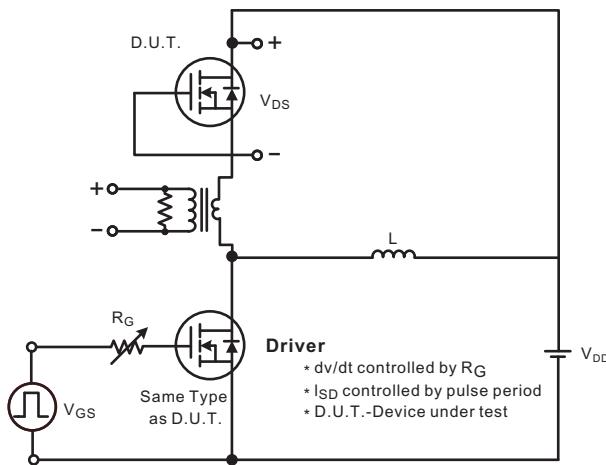


**Fig.13 Transient thermal response curve (for 7N60AF)**

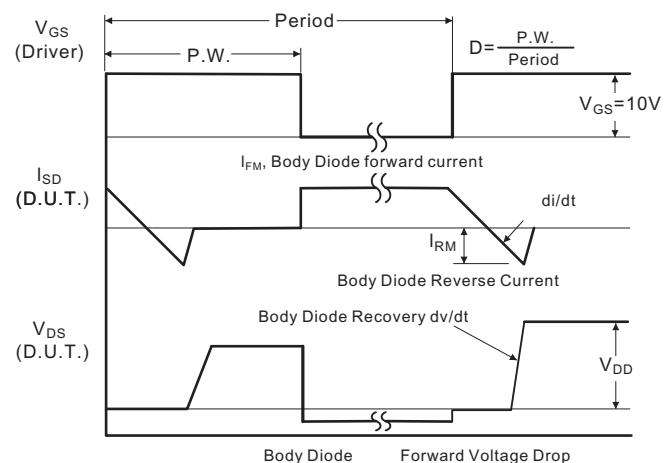


## ■ TEST CIRCUITS AND WAVEFORMS

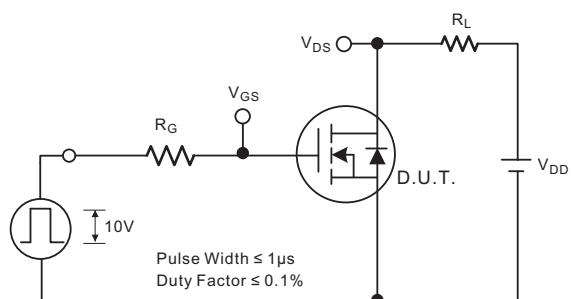
**Fig.1A Peak diode recovery dv/dt test circuit**



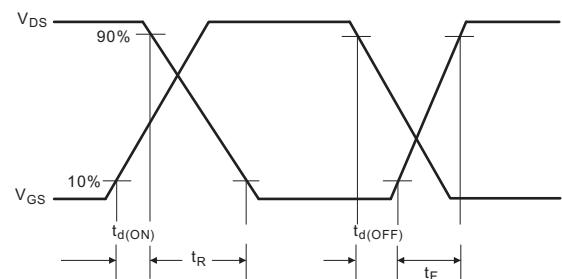
**Fig.1B Peak diode recovery dv/dt waverforms**



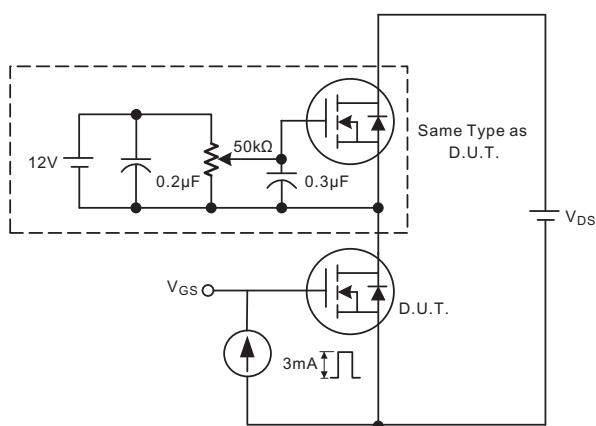
**Fig.2A Switching test circuit**



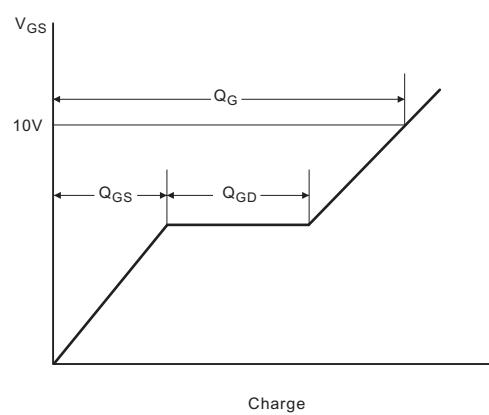
**Fig.2B Switching Waveforms**

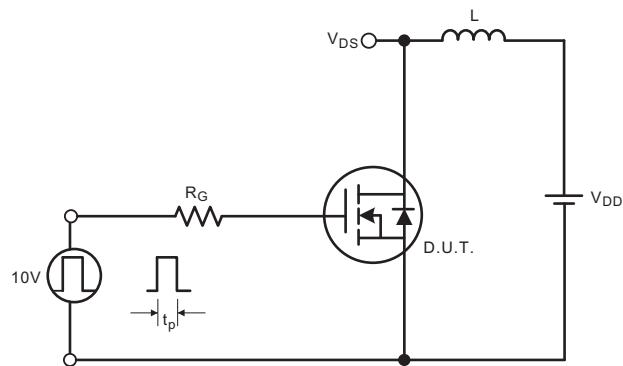
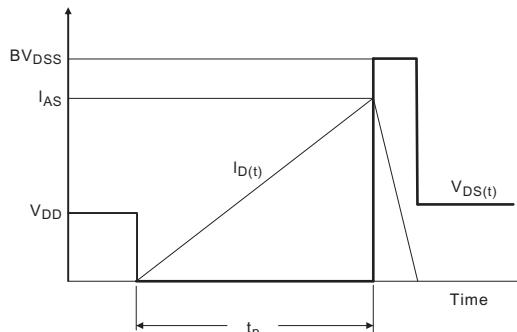


**Fig.3A Gate charge test circuit**

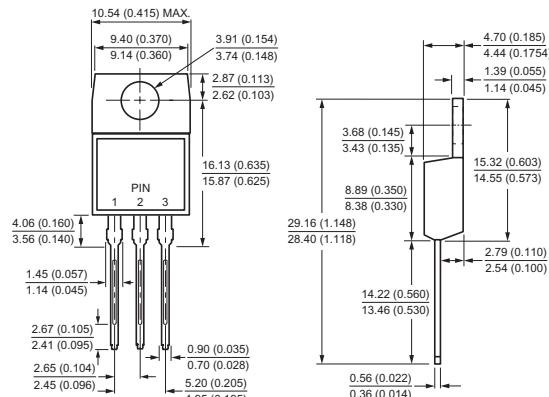
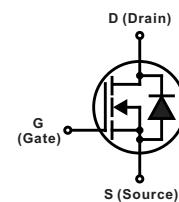
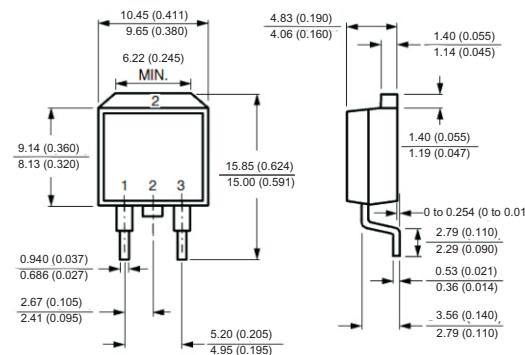


**Fig.3B Gate charge waveform**



**Fig.4A Unclamped Inductive switching test circuit**

**Fig.4B Unclamped Inductive switching waveforms**


## Case Style

**TO-220AB**

**TO-263(D<sup>2</sup>PAK)**


All dimensions in millimeters(inches)

## Case Style

